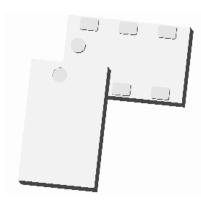




Ultra Low Profile 0805 Balun 50Ω to 100Ω Balanced



Description:

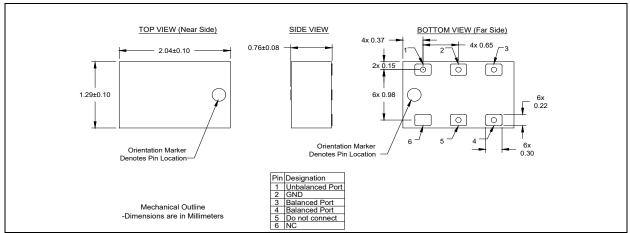
The B0310J50100AHF is a low cost, low profile sub-miniature unbalanced to balanced transformer designed for differential inputs and output locations on modern chipsets in an easy to use surface mount. The B0310J50100AHF is ideal for high volume manufacturing and delivers higher performance than traditional wire wound baluns. The B0310J50100AHF has an unbalanced port impedance of 50Ω and a 100Ω balanced port impedance*. This transformation enables single ended signals to be applied to differential ports on modern integrated chipsets. The output ports have equal amplitude (-3dB) with 180 degree phase differential. The B0310J50100AHF is available on tape and reel for pick and place high volume manufacturing.

Detailed Electrical Specifications:

•		ROOM (25°C)			
Features:	Parameter	Min.	Тур.	Max	Unit
• 300 – 1000 MHz	Frequency	300		1000	MHz
0.7mm Height Profile	Unbalanced Port Impedance		50		Ω
• 50 Ohm to 2 x 50 Ohm	Balanced Port Impedance		100		Ω
 Surface Mountable Tape & Reel Non-conductive Surface RoHS Compliant 	Return Loss	8.1	9.4		dB
	Insertion Loss*		8.0	1.0	dB
	Amplitude Balance		2.5	2.8	dB
Halogen Free	Phase Balance		34	36	Degrees
	CMRR		9		dB
	Power Handling @85°C			2.0	Watts
	Power Handling @105°C			1.3	Watts
	Operating Temperature	-55	5 00\	+140	°C

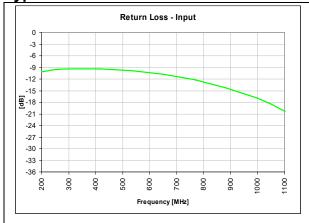
^{*} Insertion Loss stated at room temperature (Insertion Loss is approximately 0.1 dB higher at +85 °C)

Outline Drawing:

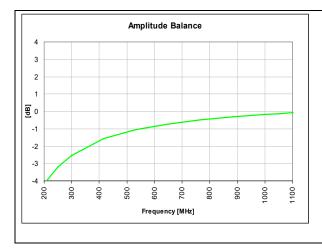


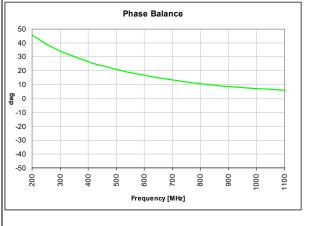


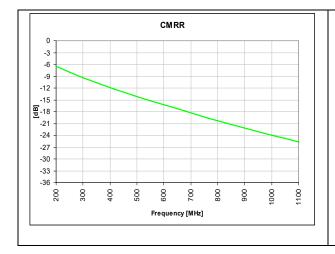
Typical Performance:





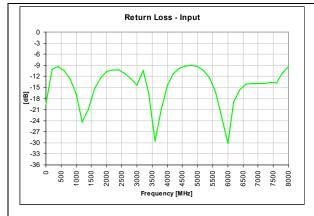


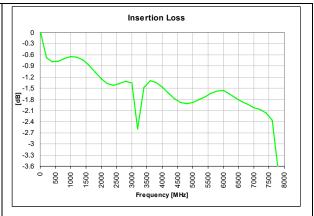


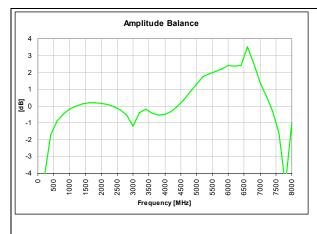


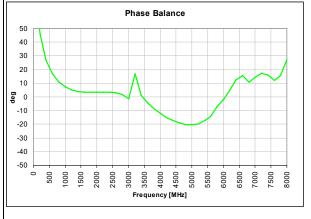


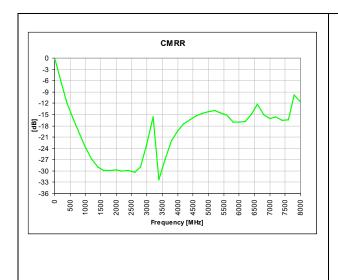
Wide Band Performance: 0 MHz to 8000 MHz

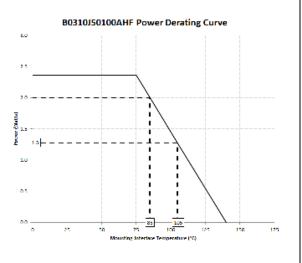












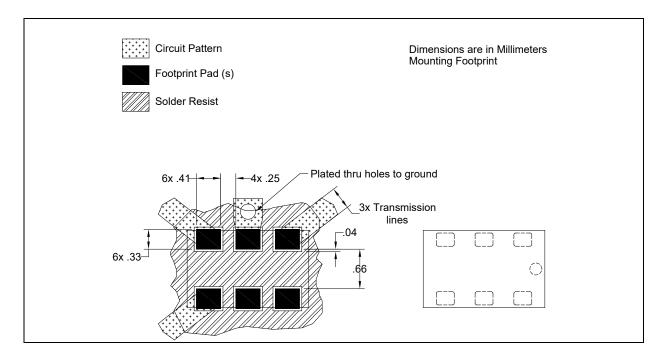


Mounting Configuration:

In order for Xinger surface mount components to work optimally, the proper impedance transmission lines must be used to connect to the RF ports. If this condition is not satisfied, insertion loss, Isolation and VSWR may not meet published specifications.

All of the Xinger components are constructed from organic PTFE based composites which possess excellent electrical and mechanical stability. Xinger components are compliant to a variety of ROHS and Green standards and ready for Pb-free soldering processes. Pads are Gold plated with a Nickel barrier.

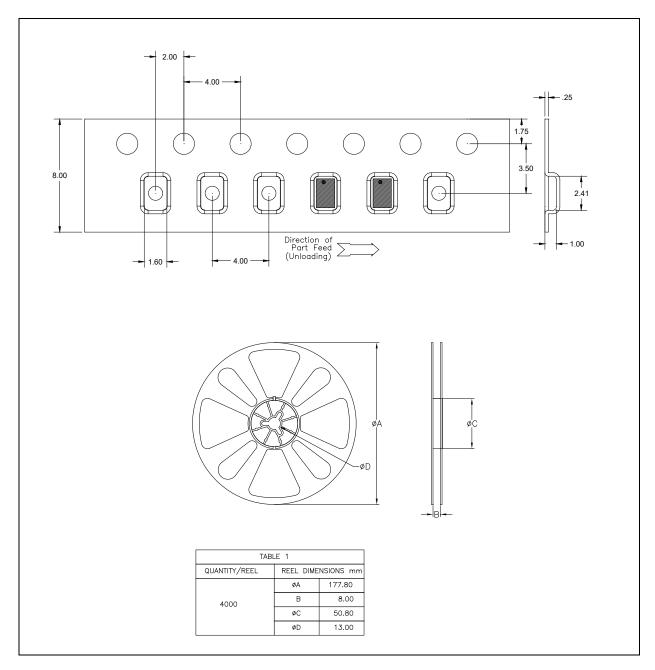
An example of the PCB footprint used in the testing of these parts is shown below. In specific designs, the transmission line widths need to be adjusted to the unique dielectric coefficients and thicknesses as well as varying pick and place equipment tolerances.





Packaging and Ordering Information:

Parts are available in reel and are packaged per EIA 481-D. Parts are oriented in tape and reel as shown below. Minimum order quantities are 4000 per reel.



Contact us:

rf&s support@ttm.com

